High-performance Liquid Cooling Heat Sink

Thermal Management Solution

Our high-performance liquid cooling heat sink with connectors is suitable for heat dissipation of high-power components with tight packaging constraints. With low thermal resistance, our robust and cost-effective solution is customizable to your end application needs.

**Low Thermal Resistance**

<0.035°C/W at 1 LPM with PG25 coolant while pressure drop is <0.05 BAR

**Material Combination Available**

Such as aluminum and copper

**High-strength Thermoplastic Encapsulation**

Liquid flow is sealed by glass-fiber reinforced thermoplastic material where absolute pressure of 5 BAR is reached without any leakage and rupture

**Increased Surface-area-to-volume Ratio**

Staggered Copper Pin Fins (0.8 mm thick, 2 mm pitch)

**Applications**

- Battery Cooling Plate
- Power Inverter
- CPU Cooler
- Avionics

**Industries**

- e-Mobility & Automotive
- Information & Communications Technology
- Aerospace

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